



**THE DATASHEET OF  
S1M-13-F**

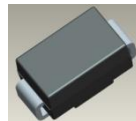


**1.0A SURFACE MOUNT GLASS PASSIVATED RECTIFIER**
**Features**

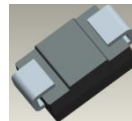
- Glass Passivated Die Construction for High Reliability
- Surge Overload Rating to 30A Peak
- Ideally Suited for Automated Assembly
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

**Mechanical Data**

- Case: SMA/SMB
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead-Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 ②③
- Polarity: Cathode Band or Cathode Notch
- Weight: SMA - 0.064 grams (Approximate)  
SMB - 0.093 grams (Approximate)



Top View



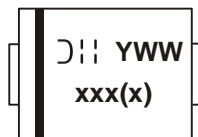
Bottom View

**Ordering Information**(Note 4)

Part Number	Qualification	Case	Packaging
S1x-13-F	Commercial	SMA	5,000/Tape & Reel
S1xB-13-F	Commercial	SMB	3,000/Tape & Reel

\* x = Device type, e.g. S1A-13-F (SMA package); S1AB-13-F (SMB package).

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

**Marking Information**


- XXX = Product Type Marking Code, ex: S1A (SMA Package)
- XXXX = Product Type Marking Code, ex: S1AB (SMB Package)
- ⌋|| = Manufacturers' Code Marking
- YWW = Date Code Marking
- Y = Last Digit of Year (ex: 4 for 2014)
- WW = Week Code (01 to 53)

**Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitance load, derate current by 20%.

Characteristic	Symbol	S1 A/AB	S1 B/BB	S1 D/DB	S1 G/GB	S1 J/JB	S1 K/KB	S1 M/MB	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$								
Working Peak Reverse Voltage	$V_{RWM}$	50	100	200	400	600	800	1000	V
DC Blocking Voltage	$V_R$								
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Average Rectified Output Current @ $T_T = +100^\circ\text{C}$	$I_O$	1.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	$I_{FSM}$	30							A

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal (Note 5)	$R_{\theta JT}$	30	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-65 to +150	$^\circ\text{C}$

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit
Forward Voltage @ $I_F = 1.0\text{A}$	$V_{FM}$	—	—	1.1	V
Peak Reverse Leakage Current @ $T_A = +25^\circ\text{C}$ at Rated DC Blocking Voltage @ $T_A = +125^\circ\text{C}$	$I_{RM}$	—	—	5.0 100	$\mu\text{A}$
Reverse Recovery Time (Note 6)	$t_{rr}$	—	1.8	3.0	$\mu\text{s}$
Typical Total Capacitance (Note 7)	$C_T$	—	10	—	pF

- Notes: 5. Thermal resistance junction to terminal, unit mounted on PC board with 5.0 mm<sup>2</sup> (0.013 mm thick) copper pads as heat sink.  
6. Measured with  $I_F = 0.5\text{A}$ ,  $I_R = 1.0\text{A}$ ,  $I_{RR} = 0.25\text{A}$ .  
7. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

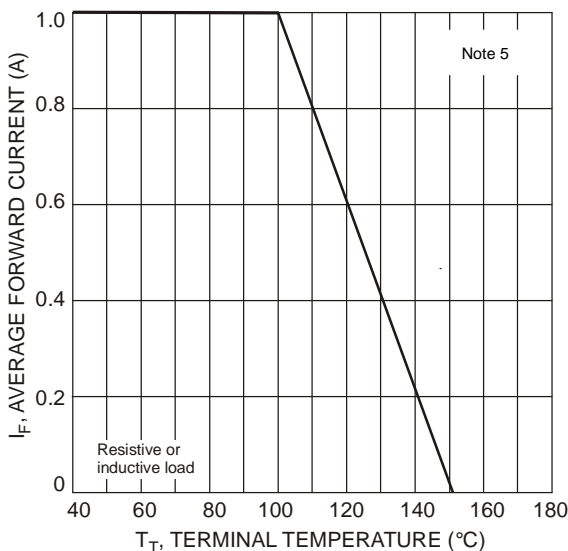


Fig. 1 Forward Current Derating Curve

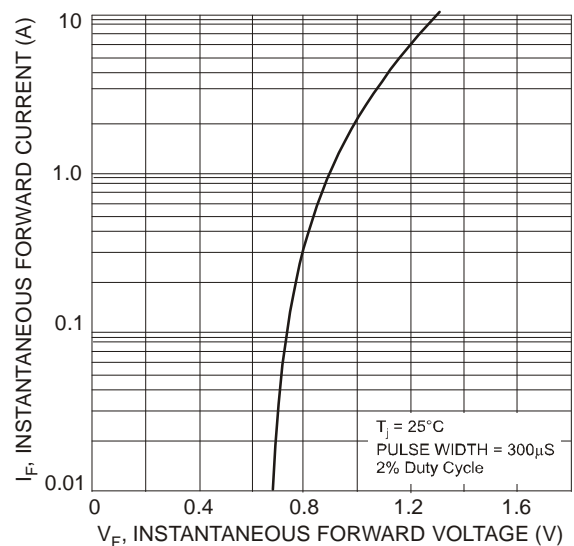


Fig. 2 Typical Forward Characteristics

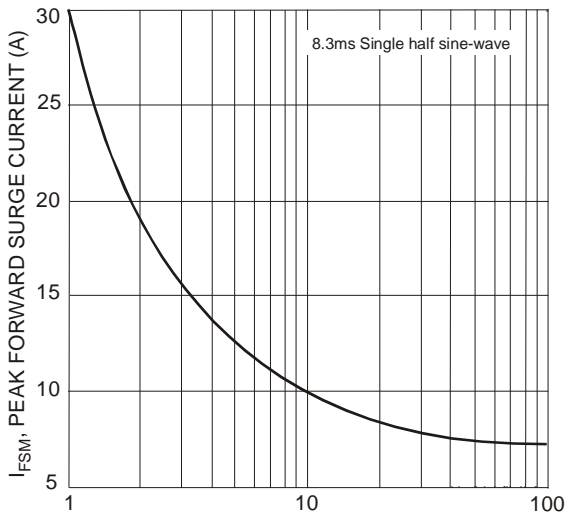


Fig. 3 Typical Forward Characteristics

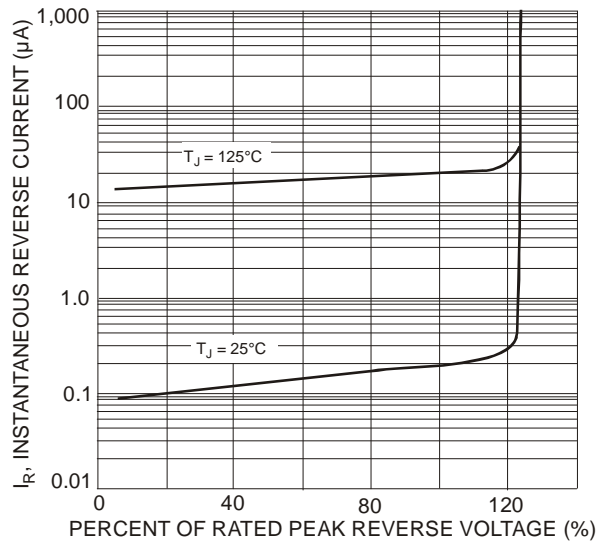
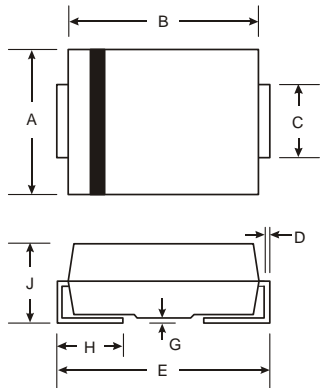


Fig. 4 Typical Reverse Characteristics

## Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SMA		
Dim	Min	Max
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.05	0.20
H	0.76	1.52
J	1.96	2.40
All Dimensions in mm		



SMB		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.57
C	1.96	2.21
D	0.15	0.31
E	5.00	5.59
G	0.05	0.20
H	0.76	1.52
J	2.00	2.50
All Dimensions in mm		



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